

AMENDMENTS TO THE CLAIMS

1. (currently amended) A chemical mechanical polishing (CMP) pad,
comprising:

a unitary body having a first side and a second side, said second side being
a polishing side;

said first side having a plurality of holes formed therein, arranged into a
concentric circular configuration; and

said second side having a plurality of grooves formed therein, arranged
into a concentric circular configuration;

wherein each of said plurality of holes in said first side is aligned with one
of said plurality of grooves in said second side;

the depth of each of said plurality of holes extends up to said one of said
plurality of grooves; and

each of said holes are sized in a manner so as not to exceed the width of a
corresponding groove aligned therewith.

2. (canceled)

3. (canceled)

4. (canceled)

5. (canceled)

6. (canceled)

7. (canceled)

8. (canceled)

9. (currently amended) A chemical mechanical polishing (CMP) pad assembly, comprising:

a sub pad attached to the upper surface of a support turntable;

a CMP pad having unitary body with a first side and a second side, said second side being a polishing side, wherein said first side is in contact with said sub pad;

said first side having a plurality of holes formed therein, arranged into a concentric circular configuration; and

said second side having a plurality of grooves formed therein, arranged into a concentric circular configuration

wherein each of said plurality of holes in said first side is aligned with one of said plurality of grooves in said second side;

the depth of each of said plurality of holes extends up to said one of said plurality of grooves; and

each of said holes are sized in a manner so as not to exceed the width of a corresponding groove aligned therewith.

10. (canceled)

11. (canceled)

12. (canceled)

13. (canceled)

14. (canceled)

15. (canceled)

16. (canceled)

17. (currently amended) A chemical mechanical polishing (CMP) assembly, comprising:

a rotatable pressure block for securing a semiconductor wafer therein;
a support turntable having a sub pad attached to the upper surface thereof;
a CMP pad having unitary body with a first side and a second side,

wherein said first side is in contact with said sub pad and said second side is disposed so as to come into contact with said semiconductor wafer during a polishing operation; and
at least one supply line for dispensing CMP fluid for said polishing operation;

wherein said first side of said CMP pad has a plurality of holes formed therein, arranged into a concentric circular configuration, and said second side of said CMP pad has a plurality of grooves formed therein, arranged into a concentric circular configuration; and

wherein each of said plurality of holes in said first side is aligned with one of said plurality of grooves in said second side;

the depth of each of said plurality of holes extends up to said one of said plurality of grooves; and

each of said holes are sized in a manner so as not to exceed the width of a corresponding groove aligned therewith.

18. (canceled)

19. (canceled)

20. (canceled)

21. (canceled)

22. (canceled)

23. (canceled)

24. (canceled)